



Wong Tsz Ho

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## Education:

The Hong Kong University of Science and Technology [2020 - now]

*MSc in Big Data Technology*

- Apache Spark
- Data Analytics Techniques
- Time Series Analysis
- Parallel Programming

The Hong Kong Polytechnic University [2015 – 2020(planned)]

*BEng(Hons) in Electronic and Information Engineering, [W GPA : 3.42]*

- Circuit Analysis and Logic Design
- Microcontroller System and Interface Design
- Embedded System Programming
- Machine Learning and IoT

Earned IBM AI Engineering Professional Certificate @ Coursera

## Skills:

**Software:** Skilled in Python, Linux, C/C++, Arduino Programming;  
Experience in Big Data Stack (Hadoop, Spark); Experience in Container Technology (Docker, Kubernetes)

## Language:

Proficient in Cantonese, Mandarin; Good command of English

## Activities:

Finspire Online Hackathon 2020;

➤ Couple Spending Companion

SmarTone Hackathon 2019;

➤ Machine Learning assisted gesture recognition on Web using JS;

Hard@UST - Finalist;

➤ Automatic Pizza making machine

Project STARS@PolyU – Gold Award

➤ Cambodia, Myanmar Exchange;

## Experiences:

*Engr Project Specialist I (Innovation Lab)/ Hewlett Packard Enterprise Jun 2020 - now*

- Container Technology: HPE Ezmeral Container Platform, Docker, Kubernetes;
- Big Data & Machine Learning Operation: HPE Ezmeral MLOps, HPE Ezmeral Data Fabric, Apache Spark;
- IoT & Edge Computing: HPE Edgeline, Apache Kafka;

*Summer Intern / Wuxi Murata Electronics Co., Ltd Jul 2019 - Aug 2019*

- Developed RPA (Robot Process Automation) program for HR department;
- Understood the industrial process of manufacturing;

*Summer Intern / Shenzhen Skyworth-RGB Electronic Co Ltd Jun 2019 - Jul 2019*

- Acquired knowledge about management of huge project (As Embedded Middleware Team);
- Acquired the proper program document writing and team management;

*Electronic Engineer Trainee (Gap-Year Intern) / RF Tech Ltd Aug 2018 - May 2019*

- Developed product of LoRa, NB-IoT and Product Development for Visualization Platform;
- Manufactured PCB including Schematics, Layout and Soldering;
- Firmware programming on IoT system of Self-service Library Station;